

M.2 (P42) 4TE2 Series

Customer:	
Customer	
Part Number:	
Innodisk	
Part Number:	
Innodisk	
Model Name:	
Date:	

Innodisk	Customer
Approver	Approver

Total Solution For Industrial Flash Storage



Features:

- PCIe Gen 4 x4, NVMe SSD
- Kioxia 3D TLC NAND
- M.2 2242-D2-M
- Standard/Wide-temperature
- iPower Guard
- iData Guard
- Dynamic Thermal Management
- 256-bit AES hardware-based encryption
- Support TCG OPAL function (Optional)
- Support PCIe PLA_S3 & PLN (Optional)

Performance:

- Sequential Read up to 3,550 MB/s
- Sequential Write up to 3,100 MB/s

Power Requirements:

Input Voltage:	3.3V± 5%
Max Operating Wattage (R/W):	5.0W
Idle Wattage:	1.6W

Reliability:

Capacity	TBW	DWPD
128GB	107	0.89
256GB	223	0.93
512GB	423	0.88
1TB	852	0.89
2ТВ	1706	0.89

Data Retention	1 Year
Warranty	3 Years

¹⁻year data retention is at NAND life end.

For warranty details, please refer to:

https://www.innodisk.com/en/support_and_service/warranty



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REVISION HISTORY

Revision	Description	Date	
V1.0	First Release	May., 2024	
V1.1	Update Product Features & User Capacity	Aug., 2024	
V1.2	Update TBW/DWPD	Aug., 2024	
	Update Product image & Mechanical Drawing		
	Update Pin Assignment		
	Add PLA_S3 & PLN		
V1.3	Update Performance	Mar., 2025	



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1. Product Overview

1.1 Introduction of Innodisk M.2 (P42) 4TE2

Innodisk M.2 (P42) 4TE2 is a NVM Express DRAM-less SSD designed with PCIe interface and industrial 3D TLC NAND Flash. M.2 (P42) 4TE2 supports PCIe Gen 4 x4 and it is compliant with NVMe 1.4 providing excellent top and also sustained performance. With sophisticated error detection and correction (ECC) functions, the module can provide full End-to-end Data Path Protection that secures the data transmission between the host system and NAND Flash.

1.2 Product View and Models

Innodisk M.2 (P42) 4TE2 is available in follow capacities with industrial 3D TLC flash ICs.

M.2 (P42) 4TE2 128GB

M.2 (P42) 4TE2 256GB

M.2 (P42) 4TE2 512GB

M.2 (P42) 4TE2 1TB

M.2 (P42) 4TE2 2TB





Figure 1: Innodisk M.2 (P42) 4TE2 (type 2242)

1.3 PCIe Interface

Innodisk M.2 (P42) 4TE2 supports PCIe Gen4 interface and compliant with NVMe 1.4. M.2 (P42) 4TE2 can work under PCIe Gen1, Gen2 and Gen3.

Most of operating system includes NVMe in-box driver now. For more information about the driver support in each OS, please visit https://nvmexpress.org/drivers/.



2. Product Specifications

2.1 Capacity and Device Parameters

M.2 (P42) 4TE2 device parameters are shown in Table 1.

Table 1: Device parameters

Capacity	Cylinders	Heads	Sectors	LBA	User Capacity(MB)		
128GB				234441648	114473		
256GB		16	16	16		468862128	228937
512GB	16383				16383 16 63 937	937703088	457863
1TB			1875385008	915715			
2TB				3750748848	1831420		

2.2 Performance

Burst Transfer Rate: 8 GB/s

Table 2: Performance- 112 Layers 3D TLC

Capacity	Unit	128GB	256GB	512GB	1TB	2ТВ
Sequential*		1,400	2,850	3,550	3,450	3,450
Read (Q8T1)		1,400	2,630	3,330	3,430	3,430
Sequential*		990	1 700	2.400	2 100	2.050
Write (Q8T1)		880	1,700	2,400	3,100	3,050
Sustained	MB/s					
Sequential Read		840	1,850	1,800	1,900	1,650
(Avg.)***						
Sustained						
Sequential Write		180	270	390	660	650
(Avg.)***						
4KB Random**		110.000	247.000	470.000	F60,000	FF0 000
Read (Q32T16)	IOPS	119,000	247,000	470,000	569,000	558,000
4KB Random**		207.000	202.000	462,000	F00,000	F40,000
Write (Q32T16)		207,000	393,000	462,000	599,000	549,000

Note: * Performance results are 4TE2 with Kioxia BiCS5 NAND composition measured in Room Temperature with Out-of-Box devices and may vary depending on overall system setup. In addition, 4TE2 series adopt hybrid mode which enables SLC cache followed by TLC direct write to strike balance between burst performance and steady overall stability. Note: ** Performance results are based on CrystalDiskMark 8.0.1 with file size 1000MB. Unit of 4KB item is IOPS.

Note: *** Performance results are based on AIDA 64 v5.98 with block size 1MB of Linear Read & Write Test Item.



2.3 Electrical Specifications

2.3.1 Power Requirement

Table 3: Innodisk M.2 (P42) 4TE2 Power Requirement

Item	Symbol	Rating	Unit
Input voltage	V_{IN}	+3.3 DC +- 5%	V

2.3.2 Power Consumption

Table 4: Power Consumption

Mode	Power Consumption (W)
Read	4.6
Write	5.0
Idle	1.6
Power-on peak	4.0

Target: M.2 (P42) 4TE2 2TB

Note: Current results may vary depending on system components and power circuit design. Please refer to the test report for other capacities.

2.4 Environmental Specifications

2.4.1 Temperature Ranges

Table 5: Temperature range for M.2 (P42) 4TE2

Temperature	Range
Operating	Standard Grade: 0°C to +70°C
Operating	Industrial Grade: -40°C to +85°C
Storage	-40°C to +85°C

2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

2.4.3 Shock and Vibration

Table 6: Shock/Vibration Testing for M.2 (P42) 4TE2

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 60068-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 60068-2-27



2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various M.2 (P42) 4TE2 configurations. The analysis was performed using a RAM Commander[™] failure rate prediction.

- **Failure Rate**: The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- **Mean Time between Failures (MTBF)**: A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Table 7: M.2 (P42) 4TE2 MTBF

Product	Condition	MTBF (Hours)
Innodisk M.2 (P42) 4TE2	Telcordia SR-332 GB, 25°C	>3,000,000

2.5 CE and FCC Compatibility

M.2 (P42) 4TE2 conforms to CE and FCC requirements.

Table 8: M.2 (P42) 4TE2 ESD

Reliability	Reference standards
Electrostatic Discharge (ESD)	EC 61000-4-2 ESD

2.6 RoHS Compliance

M.2 (P42) 4TE2 is fully compliant with RoHS directive.



2.7 Reliability

Table 9: M.2 (P42) 4TE2 TBW

Parameter	Value	
Read Cycles	Unlimited Read Cycles	
Flash endurance	3,000 P/E cycles	
Error Correct Code	Support(LDPC)	
Data Retention	Under 40°C: 1 Year at NAND Life End	
TDM/* (Total Butes Muitter) Lipit, TD		

TBW* (Total Bytes Written) Unit: TB

	•	
Capacity	Sequential workload	Client workload
128GB	341	107
256GB	682	223
512GB	1364	423
1TB	2727	852
2TB	5454	1706

^{*} Note:

- 1. Sequential: Mainly sequential write are estimated by PassMark Burnin Test v8.1 pro.
- 2. Client: Follow JESD218 Test method and JESD219A Workload, tested by ULINK. (The capacity lower than 64GB client workload is not specified in JEDEC219A, the values are estimated.)
- 3. Based on out-of-box performance.

2.8 Transfer Mode

M.2 (P42) 4TE2 support following transfer mode:

PCIe Gen4: 8 GB/s PCIe Gen3: 4 GB/s PCIe Gen2: 2 GB/s PCIe Gen1: 1 GB/s



2.9 Pin Assignment

Innodisk M.2 (P42) 4TE2 follows standard M.2 spec, socket 3 key M PCIe-based SSD pinout. See Table 10 for M.2 (P42) 4TE2 pin assignment.

Table 10: Innodisk M.2 (P42) 4TE2 Pin Assignment

Signal Name	Pin #	Pin #	Signal Name
		75	GND
3.3V	74	73	GND
3.3V	72	71	GND
3.3V	70	69	NC
NC	68	67	NC
Notch	66	65	Notch
Notch	64	63	Notch
Notch	62	61	Notch
Notch	60	59	Notch
NC	58	57	GND
NC	56	55	REFCLKp
NC	54	53	REFCLKn
CLKREQ# (I/O) (0V/1.8V/3.3V)	52	51	GND
PERST# (I) (0V/1.8V/3.3V)	50	49	PERp0
NC	48	47	PERn0
NC	46	45	GND
ALERT# (I) (0/1.8V)	44	43	PETp0
SMB_DATA (I/O) (0/1.8V)	42	41	PETn0
SMB_CLK (I/O) (0/1.8V)	40	39	GND
NC	38	37	PERp1
NC	36	35	PERn1
NC	34	33	GND
NC	32	31	PETp1
PLA_S3# (I)(0/1.8/3.3V) or NC	30	29	PETn1
NC	28	27	GND
NC	26	25	PERp2
NC	24	23	PERn2
NC	22	21	GND
NC	20	19	PETp2
3.3V	18	17	PETn2
3.3V	16	15	GND
3.3V	14	13	PERp3



3.3V	12	11	PERn3
LED1# (O) (OD)	10	9	GND
PLN# (O)(0/1.8/3.3V) or NC	8	7	PETp3
NC	6	5	PETn3
3.3V	4	3	GND
3.3V	2	1	GND



2.10 Mechanical Dimensions

M.2 Type 2242-D2-M

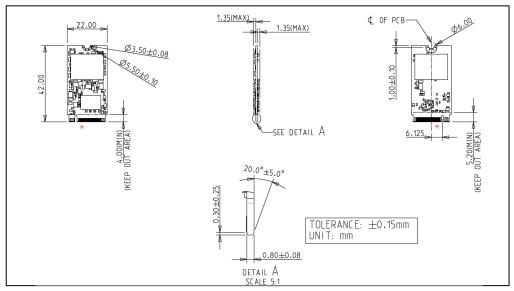


Figure 2: Innodisk M.2 (P42) 4TE2 mechanical drawing

M.2 Type 2242 with heatsink (Default accessory for WT)

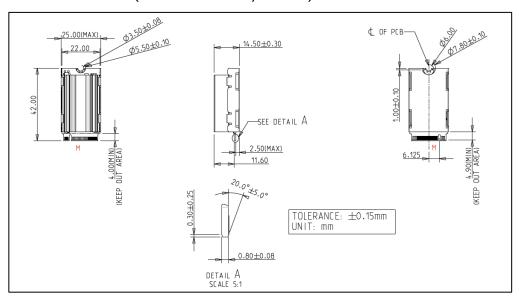


Figure 3: Innodisk M.2 (P42) 4TE2 mechanical drawing with heatsink diagram

* Note:

The appearance of silicone oil seeping out from the inside of the thermal pad is a normal occurrence. Silicone oil is not electrically conductive, so it does not impact the functionality of SSD.

2.11 Assembly Weight

An Innodisk M.2 (P42) 4TE2 within NAND flash ICs, 128GB's weight is 7 grams approximately.

2.12 Seek Time

Innodisk M.2 (P42) 4TE2 is not of magnetic rotating design. There is no seek or rotational latency.



2.13 NAND Flash Memory

Innodisk M.2 (P42) 4TE2 uses industrial 3D TLC NAND flash memory, which is non-volatility, high reliability and high speed memory storage.



3. Theory of Operation

3.1 Overview

Figure 4 shows the operation of Innodisk M.2 (P42) 4TE2 from the system level, including the major hardware blocks.

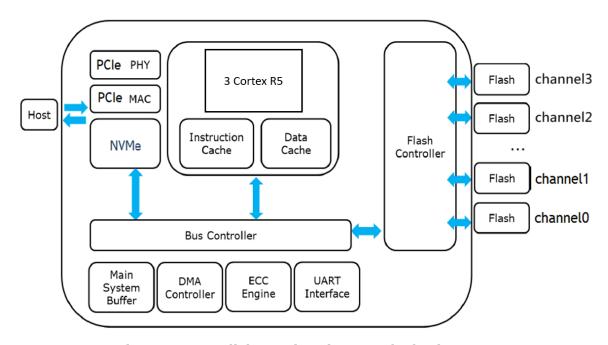


Figure 4: Innodisk M.2 (P42) 4TE2 Block Diagram

Innodisk M.2 (P42) 4TE2 integrates a PCIe Gen 4 x4 controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard NVM protocol. Communication with the flash device(s) occurs through the flash interface.

3.2 PCIe Gen 4 x4 Controller

Innodisk M.2 (P42) 4TE2 is designed with a PCIe Gen 4 x4 controller which is compliant with NVMe 1.4, up to 64.0Gbps transfer speed. In addition, it is compliant with PCIe Gen 1, Gen 2 and Gen 3 specification. The controller supports up to four channels for flash interface.

3.3 Error Detection and Correction

Innodisk M.2 (P42) 4TE2 is designed with hardware LDPC ECC engine with hard-decision and soft-decision decoding. Low-density parity-check (LDPC) codes have excellent error correcting performance close to the Shannon limit when decoded with the belief-propagation (BP) algorithm using soft-decision information.



3.4 Wear-Leveling

Flash memory can be erased with a limited number of cycles. This number is called the **erase cycle limit** or **write endurance limit** and is defined by the flash NAND vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk M.2 (P42) 4TE2 uses a combination of two types of wear leveling- dynamic and static wear leveling- to distribute write cycling across an SSD and balance erase count of each block, thereby extending device lifetime.

3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the lifetime of the SSD. When a Bad Block is detected, it will be flagged as unusable block by firmware. The SSD implement Bad Blocks management that consists of Bad Blocks replacement and Error Correcting to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

3.6 Garbage Collection/TRIM

Garbage collection and TRIM technology is used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD's speed and lifespan.

3.7 End to End Data Path Protection

End-to-end Data Path Protection that secures the data transmission between host system and NAND Flash. In the transmission path, no matter in or out, all buffer and storage implement Error Code Correction that optimizes the data integrity in the whole transmission of SSD.

3.8 Thermal Management

M.2 (P42) 4TE2 has built-in thermal sensor which can detect environment temperature of SSD. In the meantime, firmware will monitor the thermal sensor to prevent any failure of overheating. During extreme temperature, firmware will adjust the data transfer behavior to maintain the SSD's reliable operation.

3.9 Thermal Throttling

Thermal throttling is a protective mechanism designed to safeguard components from potential damage caused by excessive temperatures. When an SSD approaches a critical temperature threshold, Innodisk firmware activates the thermal throttling mechanism to regulate the SSD's temperature. Thermal throttling is crucial for SSDs since it prevents drive damage, which could



otherwise result in data loss. However, it's worth noting that when thermal throttling is activated, read and write tasks may experience a reduction in speed.

3.10 iData Guard

iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to the SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.

3.11 TCG OPAL (Optional)

OPAL is a set of specifications for features of data storage devices that enhance security. These specifications are published by the Trusted Computing Group's Storage Work Group. Innodisk 4TE2 is compliant with TCG OPAL 2.0(*1). The capability of TCG OPAL Security mode allows multiple users with independent access control to read/write/erase independent data areas (LBA ranges). Each locking range adjusts by authenticated authority. Note that by default there is a single "Global Range" that encompasses the whole user data area. In TCG Opal Security Mode, Revert, Revert SP and GenKey command can erase all of data including global range and locking range; in the meantime generate the new encrypted key.

*1. You need to install TCG OPAL software to implement OPAL function, which is supplied by TCG OPAL software developed company

3.12 PLA_S3# (Optional)

Power Loss Acknowledge. Open drain with pull-up on Platforms that support power loss notification. An Adapter that supports this function must drive the signal to reflect its current power loss processing complete state.

3.13 PLN (Optional)

Power Loss Notification. Open drain with a pull-up on Adapters that support power loss notification. When the Platform supports power loss notification, this signal is asserted to indicate a power loss event is expected to occur. When the Adapter supports this function and the signal is asserted then it must ready itself for power loss.



4. Installation Requirements

4.1 M.2 (P42) 4TE2 Pin Directions

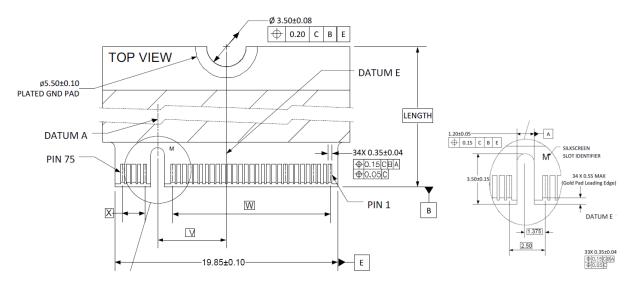


Figure 5: Signal Segment and Power Segment

4.2 Electrical Connections for M.2 (P42) 4TE2

M.2 interconnect is based on a 75 position Edge Card connector. The 75 position connector is intended to be keyed so as to distinguish between families of host interfaces and the various Sockets used in general Platforms. M.2 (P42) 4TE2 is compliant with M.2 Socket 3 key M.

4.3 Device Drive

M.2 (P42) 4TE2 is compliant with NVMe 1.4. Both Operation System and BIOS should include NVMe driver to compatible with NVMe device. Nowadays, most of OS includes NVMe in-box driver now. For more information about the driver support in each OS, please visit the website https://nvmexpress.org/drivers/. For BIOS NVMe driver support please contact with motherboard manufacturers.



5. SMART / Health Information

This log page is used to provide SMART and general health information. The information provided is over the life of the controller and is retained across power cycles. More details about Set Features command; please refer to NVM Express 1.4

5.1 Get Log Page (Log Identifier 02h)

Innodisk 4TE2 series SMART / Health Information Log are listed in following table.

Table 11: Get Log Page - SMART / Health Information Log

tes	Descriptio	n				
	Critical Warning: This field indicates critical warnings for the state of the controller. Each bit					
	corresponds to a critical warning type; multiple bits may be set to `1'. If a bit is cleared to `0					
	then that critical warning does not apply. Critical warnings may result in an asynchronous event					
	notification	to the host. Bits in this field represent the state at the time the Get Log Page				
	command is	s processed and may not reflect the state at the time a related asynchronous eve				
	notification,	, if any, occurs or occurred.				
	Bit	Definition				
	0	If set to '1', then the available spare capacity has fallen below the				
		threshold.				
	1	If set to `1', then a temperature is:				
		a) greater than or equal to an over temperature threshold.				
0		b) less than or equal to an under temperature threshold.				
	2	If set to `1', then the NVM subsystem reliability has been degraded due to				
		significant media related errors or any internal error that degrades NVM				
		subsystem reliability.				
	3	If set to `1', then all of the media has been placed in read only mode. The				
		controller shall not set this bit to '1' if the read-only condition on the media				
		is a result of a change in the write protection state of a namespace.				
	4	If set to `1', then the volatile memory backup device has failed. This field is				
		only valid if the controller has a volatile memory backup solution.				
	5	If set to `1', then the Persistent Memory Region has become read-only or				
		unreliable.				
	7:6	Reserved				
	1.1					



	Composite T	emperature: Contains a value corresponding to a temperature in degrees Kelvin		
	that represents the current composite temperature of the controller and namespace(s)			
	associated with that controller. The manner in which this value is computed is implementation			
1:2	specific and may not represent the actual temperature of any physical point in the NVM			
	subsystem. T	he value of this field may be used to trigger an asynchronous event.		
	Warning and	critical overheating composite temperature threshold values are reported by the		
	WCTEMP and	CCTEMP fields in the Identify Controller data structure.		
	Available Spare: Contains a normalized percentage (0 to 100%) of the remaining spare			
3	capacity available.			
	Available Sp	pare Threshold: When the Available Spare falls below the threshold indicated in		
4	this field, an a	asynchronous event completion may occur. The value is indicated as a normalized		
	percentage (0	to 100%). The values 101 to 255 are reserved.		
	Percentage	Used: Contains a vendor specific estimate of the percentage of NVM subsystem life		
	used based o	n the actual usage and the manufacturer's prediction of NVM life. A value of 100		
	indicates that	the estimated endurance of the NVM in the NVM subsystem has been consumed,		
5	but may not ir	ndicate an NVM subsystem failure. The value is allowed to exceed 100. Percentages		
	greater than 254 shall be represented as 255. This value shall be updated once per power-on			
	hour (when the controller is not in a sleep state).			
	Refer to the JEDEC JESD218A standard for SSD device life and endurance measurement			
	techniques.			
	Endurance (Group Critical Warning Summary: This field indicates critical warnings for the		
	state of Endu	rance Groups. Each bit corresponds to a critical warning type, multiple bits may be		
	set to '1'. If a	a bit is cleared to '0', then that critical warning does not apply to any Endurance		
	Group. Critica	Il warnings may result in an asynchronous event notification to the host. Bits in this		
	field represen	t the current associated state and are not persistent.		
	If a bit is set	to '1' in one or more Endurance Groups, then the corresponding bit shall be set to		
	`1' in this field	1.		
	Bit	Definition		
6	0	If set to `1', then the available spare capacity of one or more Endurance		
		Groups has fallen below the threshold.		
	1	Reserved		
	2	If set to `1', then the reliability of one or more Endurance Groups has been		
		degraded due to significant media related errors or any internal error that		
		degrades NVM subsystem reliability.		
		, , ,		
	3	If set to `1', then the namespaces in one or more Endurance Groups have		
	3			
	3	If set to `1', then the namespaces in one or more Endurance Groups have		
	7:4	If set to '1', then the namespaces in one or more Endurance Groups have been placed in read only mode not as a result of a change in the write		



7:31	Reserved								
32:47	Data Units Read: Contains the number of 512 byte data units the host has read from the controller as part of processing a SMART Data Units Read Command; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1,000 units of 512 bytes read) and is rounded up (e.g., one indicates that the number of 512 byte data units read is from 1 to 1,000, three indicates that the number of 512 byte data units read is from 2,001 to 3,000). Refer to the specific I/O Command Set specification for the list of SMART Data Units Read Commands that affect this field. A value of 0h in this field indicates that the number of SMART Data Units Read is not reported.								
48:63	Data Units Written: Contains the number of 512 byte data units the host has written to the controller as part of processing a User Data Out Command; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1,000 units of 512 bytes written) and is rounded up (e.g., one indicates that the number of 512 byte data units written is from 1 to 1,000, three indicates that the number of 512 byte data units written is from 2,001 to 3,000). Refer to the specific I/O Command Set specification for the list of User Data Out Commands that affect this field. A value of 0h in this field indicates that the number of Data Units Written is not reported.								
64:79	Host Read Commands: Contains the number of SMART Host Read Commands completed by the controller. Refer to the specific I/O Command Set specification for the list of SMART Host Read Commands that affect this field.								
80:95	Host Write Commands: Contains the number of User Data Out Commands completed by the controller. Refer to the specific I/O Command Set specification for the list of User Data Out Commands that affect this field.								
96:111	Controller Busy Time: Contains the amount of time the controller is busy with I/O commands. The controller is busy when there is a command outstanding to an I/O Queue (specifically, a command was issued via an I/O Submission Queue Tail doorbell write and the corresponding completion queue entry has not been posted yet to the associated I/O Completion Queue). This value is reported in minutes.								
112:127	Power Cycles: Contains the number of power cycles.								
128:143	Power On Hours: Contains the number of power-on hours. This may not include time that the controller was powered and in a non-operational power state.								
144:159	Unsafe Shutdowns: Contains the number of unsafe shutdowns. This count is incremented when the controller does not report it is safe to power down prior to loss of main power.								



160:175	Media and Data Integrity Errors: Contains the number of occurrences where the controller											
	detected an unrecovered data integrity error. Errors such as uncorrectable ECC, CRC checksum											
	failure, or LBA tag mismatch are included in this field. Errors introduced as a result of a Write											
	Uncorrectable command (refer to the NVM Command Set Specification) may or may not be											
	included in this field.											
176:191	Number of Error Information Log Entries: Contains the number of Error Information log											
170.131	entries over the life of the controller.											
	Warning Composite Temperature Time: Contains the amount of time in minutes that the											
	controller is operational and the Composite Temperature is greater than or equal to the Warning											
192:195	Composite Temperature Threshold (WCTEMP) field and less than the Critical Composite											
192.193	Temperature Threshold (CCTEMP) field in the Identify Controller data structure in Figure 275.											
	If the value of the WCTEMP or CCTEMP field is 0h, then this field is always cleared to 0h											
	regardless of the Composite Temperature value.											
	Critical Composite Temperature Time: Contains the amount of time in minutes that the											
	controller is operational and the Composite Temperature is greater than or equal to the Critical											
196:199	Composite Temperature Threshold (CCTEMP) field in the Identify Controller data structure.											
	If the value of the CCTEMP field is 0h, then this field is always cleared to 0h regardless of the											
	Composite Temperature value.											
200:201	Temperature Sensor 1: Contains the current temperature reported by the embedded thermal											
	sensor in the controller.											
202:203	Temperature Sensor 2: Contains the current temperature reported by the embedded thermal											
	sensor in the NAND Flash (Channel #0 and CE #0).											
204:205	Temperature Sensor 3: Contains the current temperature reported by the embedded thermal											
	sensor in the NAND Flash (Channel #0 and CE #0).											
206:207	Temperature Sensor 4: Contains the current temperature reported by the embedded thermal											
	sensor in the NAND Flash (Last channel and CE #0).											
208:209	Temperature Sensor 5: Contains the current temperature reported by temperature sensor 5.											
210:211	Temperature Sensor 6: Contains the current temperature reported by temperature sensor 6.											
212:213	Temperature Sensor 7: Contains the current temperature reported by temperature sensor 7.											
214:215	Temperature Sensor 8: Contains the current temperature reported by temperature sensor 8.											
	Thermal Management Temperature 1 Transition Count: Contains the number of times the											
216:219	controller transitioned to lower power active power states or performed vendor specific thermal											
	management actions while minimizing the impact on performance in order to attempt to reduce											
	the Composite Temperature because of the host controlled thermal management feature.											
	Thermal Management Temperature 2 Transition Count: Contains the number of times the											
220:223	controller transitioned to lower power active power states or performed vendor specific thermal											
	management actions regardless of the impact on performance (e.g., heavy throttling) in order											
	to attempt to reduce the Composite Temperature because of the host controlled thermal											
	management feature.											



	Total Time For Thermal Management Temperature 1: Contains the number of seconds that										
	the controller had transitioned to lower power active power states or performed vendor specific										
224:227	thermal management actions while minimizing the impact on performance in order to attempt to										
	reduce the Composite Temperature because of the host controlled thermal management										
	feature.										
	Total Time For Thermal Management Temperature 2: Contains the number of seconds that										
	the controller had transitioned to lower power active power states or performed vendor specific										
228:231	thermal management actions regardless of the impact on performance (e.g., heavy throttling)										
	in order to attempt to reduce the Composite Temperature because of the host controlled thermal										
	management feature.										
232:337	Reserved										
338:345	Later Bad Count										
346:353	Power-On hours Count										
354:361	Drive Power Cycle Count										
362:369	Total Bad Block Count										
370:377	User Max Erase Count										
378:385	User Avg Erase Count										
386:393	Device Life										
394:401	Spare Block Count										
402:409	Program Fail Count										
410:417	Erase Fail Count										
418:425	Unexpected Power Loss Count										
426:433	Temperature (Kelvin - K °K)										
434:441	Flash ID										
442:449	Later Bad Block Info (Read / Write / Erase)										
450:457	Total LBAs Written (unit = 32MB)										
458:465	Total LBAs Read (unit = 32MB)										



6. Part Number Rule

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	
CODE	D	E	М	2	4	-	0	2	Т	D	F	1	K	w	A	Q	F	(H)	-	x	x	X	
	Definition																						
Code 1 st (Disk)												Code 14 th (Operation Temperature)											
D : Disk											C:	Stan	dard	Grad	de (0	°C~	+70°	°C)					
		C	ode	2 nd (Feat	ture	set)				W:	Indu	ıstria	ıl Gra	ide (-40°C	_~ +	85°C)					
E : Em	bedo	led s	eries	;																			
		Cod	e 3 rd	~5 ^t	h (Fo	orm	facto	or)				Code 15 th (Internal control)											
M24: M	1.2 T	ype :	2242								A~	A~Z: BGA PCB version.											
			de 7	' th ~!	9 th (Capa	acity)				Code 16th (Channel of data transfer)											
A28: 1												D: Dual Channels											
B56: 2											Q:	Q: Quad Channels											
C12: 5	12G	3																					
01T: 1	ТВ																						
02T: 2	ТВ																						
C 10th													Co	do 1	7 th /	Elac	sh Tvn	<u></u>					
Code 10 th ~12 th (Controller) DF1: PCIe 4TE2 series										F: I	Code 17 th (Flash Type) F: Kioxia 3D TLC												
DF2: P					th AE	S & -	TCG (OPAL	. fund	ction	-												
Code 13 th (Flash mode)										Code 18 th (Optional Function)													
K: 112 Layers 3D TLC										Н:	H: with heatsink accessory (WT default)												
										Code 21 st ~ (Customize code)													

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